Joint Meeting of the IEEE P802.3cw DWDM Systems Task Force, IEEE P802.3df 400 Gb/s and 800 Gb/s Ethernet Task Force and IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

Unapproved Meeting Minutes, prepared by John D'Ambrosia, Mark Nowell, and Kent Lusted

15 May 2023
May 2023 interim
IEEE P802.3cw Task Force May 2023 Meeting Task Force Page – same as P802.3dj (see below)
IEEE P802.3df Task Force May 2023 Meeting Task Force Page - same as P802.3dj (see below)
IEEE P802.3dj Task Force May 2023 Meeting Task Force Page - https://www.ieee802.org/3/dj/public/23_03/index.html

Session called to order at 8:02 a.m. central time (all times central) by John D'Ambrosia, Chair of P802.3cw, P802.3dj and P802.3df Task Forces.

Mark Nowell, Vice-Chair of P802.3dj and P802.3df Task Forces, reminded participants to declare their name and affiliation in the online meeting tool. Failure to declare would result in expulsion from the meeting.

Chair noted that every attendee at any IEEE 802 interim meeting (Face-to-Face or Remote) must pay a fee to participate. (see slide #2)

Chair noted that the meeting would be a joint Task Force meeting of the P802.3cw Task Force, the P802.3df Task Force and the P802.3dj Task Force, as approved in the March 2023 IEEE 802.3 Working Group meeting. (see slide #3).

Agenda:

Title	Agenda and General Information
Presenters	John D'Ambrosia
URL	https://www.ieee802.org/3/dj/public/23_05/agenda_3cwdfdj_a_2305.pdf

Chair welcomed everyone to the meeting.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Chair reviewed the agenda (Slide #4) and noted presentation order (Slides #23-26).   Chair noted that individuals should check the webpage for the latest version of each presentation. Chair noted that all of the presentation times were subject to change.

Chair asked if there were any objections to the agenda. There were none. The agenda was considered approved by unanimous consent.

Chair noted that there were several Task Force and ad hoc meeting minutes to approve (see slide #5)

- IEEE P802.3cw Oct 2022 Electronic Interim:
  https://www.ieee802.org/3/cw/public/22_10/minutes_3cw_2210_unapproved.pdf
- Joint P802.3df / .3dj TF Mtg – Mar 2023 Session:
  https://www.ieee802.org/3/dj/public/23_03/minutes_3dfdj_a_2303_unapproved.pdf
- Ad hoc Meetings
  - P802.3df Logic Ad hoc –
    - 26 Apr 2023: https://www.ieee802.org/3/df/public/adhoc/logic/23_0426/minutes.pdf
  - P8023dj Joint Logic / Optics Ad hoc Meetings
    - 27 Apr 2023:
      https://www.ieee802.org/3/dj/public/adhoc/optics/0423_OPTX/minutes_3dj_optx_230427_unapproved.pdf
  - P802.3dj Electrical Ad hoc
    - 04 May 2023:
      https://www.ieee802.org/3/dj/public/adhoc/electrical/23_0504/minutes_3dj_elec_230504_unapproved.pdf

Chair asked if there were any corrections or modifications to the posted minutes. There were none.   Chair asked if there were any objections to approving the minutes. There were none, and the minutes were considered approved by unanimous consent.

Chair reviewed meeting decorum. (See Slide #6) Chair asked if there were any members of the press present. No one responded.

Chair reviewed attendance. (See Slide #7) Chair noted that Task Force meeting attendance would be through the IEEE Meeting Attendance (IMAT).

Chair reviewed the Task Force Project Information / Organization for the P802.3cw, P802.3df and the P802.3df Task Forces. (See Slides #8-10).

Chair reviewed ground rules. (See Slide #12)

Chair reviewed the current state of the Task Force. (See Slide #13-14.)

Chair reviewed voting in the task force. (See Slide #15) Chair noted that the straw polls would use the online Zoom tool. Motions would be taken with the Direct Vote Live tool if there was not unanimous consent. Chair noted that he reserved the right to take informative straw polls by 802.3 WG voting membership.

Slide #16 - Chair noted that the information regarding the IEEE SA Policies had been sent out via the Task Force reflector , and requested that individuals review the following IEEE SA policies prior to the interim meeting –
- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy and IEEE Code of Ethics

Chair asked if anyone needed to review the policies at that time – there were no requests to do so from in-person nor remote attendees.

Chair presented the third slide (See Slide #43) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #48) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair reminded participants of the IEEE Code of Ethics and Conduct. (See slide #51) He noted "All participants in IEEE-SA activities are expected to adhere to the core principles underlying the IEEE Code of Ethics and IEEE Code of Conduct"

Chair presented the second slide (See Slide #52) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair reviewed the list of liaisons for consideration. (see slide #17) There was an incoming liaison from ITU-T SG15 to IEEE 802.3 for consideration by the 3dj Task Force. Also, there was a proposed liaison response for consideration by the 3cw Task Force later in the week.

Chair noted an error on slide #18 with the status of the optical PMDs and would update the agenda presentation.

Chair reviewed the ad hoc summaries. The summaries from the P802.3df architecture ad hoc and the P802.3dj joint logic/optical ad hoc were posted to the website. (see: https://www.ieee802.org/3/df/public/23_05/gustlin_3df_01_2305.pdf and https://www.ieee802.org/3/dj/public/23_05/nowell_3dj_01_2305.pdf)

Chair reminded participants that all contributions must be submitted with the PDF document properties properly completed. If the properties are not correct, the contribution would be returned. (see: https://www.ieee802.org/3/B400G/email/msg00762.html)

Kent Lusted noted that he sent a summary of the requests to pull comments from the P802.3df D2.0 bucket1 received before the deadline. He asked participants to review the list and contact the leadership if a request was missed. (see: https://www.ieee802.org/3/B400G/email/msg00763.html)

Presentation #1

Title	**IEEE P802.3dj Electrical Ad Hoc Update**
Presenters	Kent Lusted
URL	https://www.ieee802.org/3/dj/public/23_05/lusted_3dj_01_2305.pdf

Chair noted that the backplane topic was scheduled for Tuesday, 16 May and thanked the authors for following the process that the chair requested for offline consensus building.

John D'Ambrosia passed the meeting chair responsibilities to Mark Nowell.

Presentation #2

Title	**Motions and State of the Task Force**
Presenters	John D'Ambrosia

URL	https://www.ieee802.org/3/dj/public/23_05/dambrosia_3dj_01a_2305.pdf

There was an error on slide 5 and 6. He would provide an updated version '01a'.

John D'Ambrosia resumed the meeting chair responsibilities.

Presentation #3

Title	**Reference Package Model Update for 200G/Lane Electrical I/Os**
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_02_2305.pdf

Prior to the start of presentation #4, the author had an updated presentation with editorial changes in version '03a'. Chair would post it to the website.

Presentation #4

Title	**Updated 200G Chip to Module Channels**
Presenters	Nathan Tracy
URL	https://www.ieee802.org/3/dj/public/23_05/shanbhag_3dj_03_2305.pdf

Chair noted that he received a channel contribution associated with the presentation and the channel files would be announced over the TF email reflector when posted.   Author noted that these channels should replace the versions that were currently posted.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Chair noted that Mike Li had provided updated contributions version '03a' with editorial changes to remove vendor references and the Chair would upload them to the website later in the day.

Presentation #5

Title	**224 Gbps-PAM4 Chip-to-Module Link Simulation and Analysis with a "Universal Port" Channel: Design A**
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_04_2305.pdf

Chair noted that the channel referenced in the contribution was posted to the Task Force website and asked the author to briefly review it. (see: https://www.ieee802.org/3/dj/public/23_05/li_3dj_03a_2305.pdf)

Presentation #5 Reference

Title	A 224 Gbps-PAM4 Chip-to-Module Channel for "Universal Port" and Its Characteristics: Design A
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_03a_2305.pdf

Mike Li and Sam Kocsis noted that new channel data associated with the presentation would be provided in the near future.

Break at 10:00 a.m. Resumed at 10:20 a.m.

Chair noted that he updated the website with a proposed draft liaison to the ITU for review by the participants. It would be considered during closing business on Thursday. (see: https://www.ieee802.org/3/dj/public/23_05/effenberger_3dj_01b_2305_Redacted.pdf)

Chair noted that Mike Li had provided updated contributions version '06a' and '05a' with editorial changes to remove vendor references and the Chair would upload them to the website later in the day.

Presentation #6

Title	224 Gbps-PAM4 Chip-to-Module Link Simulation and Analysis with a "Universal Port" Channel: Design B
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_06a_2305.pdf

Chair noted that the channel referenced in the contribution was posted to the Task Force website and asked the author to briefly review it. (see: https://www.ieee802.org/3/dj/public/23_05/li_3dj_05a_2305.pdf)

Presentation #6 Reference

Title	A 224 Gbps-PAM4 Chip-to-Module Channel for "Universal Port" and Its Characteristics: Design B
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_05a_2305.pdf

Author noted that the contribution needs an update to version '03a' because it has a vendor reference on slide 7.

Chair noted that updates to the website would be posted later in the day.

Prior to the start of presentation #7, the author had an updated presentation with technical and editorial changes in version '02a'. Chair asked if there was objection to hearing the updated contribution. No one responded. Chair would post it to the website.

Presentation #7

Title	200 Gbps/lane AUI C2M Channel Selection Criteria
Presenters	Kent Lusted
URL	https://www.ieee802.org/3/dj/public/23_05/lusted_3dj_02a_2305.pdf

Author noted a typo in the contribution where "VI" should be "IV" and would provide an updated version '02a'.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Prior to the start of the presentation from Tobey Li, the author had an updated presentation with editorial changes in version '01a'. Chair would post it to the website.

Presentation #8

Title	200 Gbps/Lane AUI C2C Considerations
Presenters	Tobey P.-R. Li
URL	https://www.ieee802.org/3/dj/public/23_05/lit_3dj_01a_2305.pdf

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Break at 11:50 a.m. Resumed at 1:15 p.m.

Prior to the start of the presentation from Ali Ghiasi, the author had an updated presentation with additional supporters in version '01a'. Chair would post it to the website.

Presentation #9

Title	Updated CRU Bandwidth Recommendation for 200G Interfaces
Presenters	Ali Ghiasi
URL	https://www.ieee802.org/3/dj/public/23_05/ghiasi_3dj_01a_2305.pdf

Author would provide an updated presentation version '01a' to remove the "AUI" reference in the recommendation and the straw poll on slides 7 and 8.

Presentation #10

Title	**Considerations for use of the MLSE model in COM**
Presenters	Adam Healey
URL	https://www.ieee802.org/3/dj/public/23_05/healey_3dj_01_2305.pdf

Chair asked the author to discuss possible straw polls with the electrical track chair.

Presentation #11

Title	**Updated 200G Passive Copper Cable Assembly CR Channels**
Presenters	Nathan Tracy
URL	https://www.ieee802.org/3/dj/public/23_05/shanbhag_3dj_01a_2305.pdf

Chair noted that he received a channel contribution associated with the presentation and the channel files would be announced over the TF email reflector when posted.   Author noted that these channels should replace the versions that are currently posted.

Prior to the start of the presentation from Sam Kocsis, the author had provided an updated presentation with editorial changes in version '01a'. Chair would post it to the website.

Presentation #12

Title	**Copper Cable Channel Characteristics**
Presenters	Sam Kocsis
URL	https://www.ieee802.org/3/dj/public/23_05/kocsis_3dj_01a_2305.pdf

Author noted that channel contributions would be coming in the near future.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance. Kent Lusted noted that neither he nor the WG Recording Secretary Jon Lewis would update attendance records after the meeting ends for the day.

Meeting break at 3:05 p.m.   Meeting reconvened at 3:15 p.m.

Prior to the start of the presentation from Mike Li, the author had an updated presentation with editorial changes in version '01a'. Chair would post it to the website.

Presentation #13

Title	Demonstration of a 224 Gbps-PAM4 CR SERDES in Supporting a 1 Meter Passive DAC Long Reach Channel
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_01a_2305.pdf

Chair noted that Mike Li had provided updated contributions version '08a' and '07a' with editorial changes to remove vendor references and would upload them to the website later in the day.

Presentation #14

Title	224 Gbps-PAM4 Long Reach Link Simulation and Analysis with a 1 Meter DAC Channel: Design A
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_08a_2305.pdf

Chair noted that the channel referenced in the contribution was posted to the Task Force website and asked the author to briefly review it. (see: https://www.ieee802.org/3/dj/public/23_05/li_3dj_07a_2305.pdf)

Presentation #14 Reference

Title	A 224 Gbps-PAM4 1 Meter DAC Long Reach Channel and its Characteristics: Design A
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_07a_2305.pdf

Author noted that the contribution needs an update to version '07a' because it has a vendor reference on slide 7.

Chair noted that Mike Li had provided updated contributions version '10a' and '09a' with editorial changes to remove vendor references and the Chair would upload them to the website later in the day.

Presentation #15

Title	224 Gbps-PAM4 Long Reach Link Simulation and Analysis with a 1 Meter DAC Channel: Design B
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_10a_2305.pdf

Chair noted that the channel referenced in the contribution was posted to the Task Force website and asked the author to briefly review it. (see: https://www.ieee802.org/3/dj/public/23_05/li_3dj_09a_2305.pdf)

Title	**A 224 Gbps-PAM4 1 Meter DAC Long Reach Channel and its Characteristics: Design B**
Presenters	Mike Li
URL	https://www.ieee802.org/3/dj/public/23_05/li_3dj_09a_2305.pdf

Author noted that the contribution needs an update to version '09a' because it has a vendor reference on slide 7.

At the start of straw polls, the first straw poll shown was on the RS544 for backplane/copper cables and the second straw poll shown was for the signaling type for backplane/copper cables. There was a request to swap the order of modulation straw poll prior to the RS-FEC straw poll. Chair asked if there was an objection. There were no objections. The order was swapped.

Straw Poll #1:
I would support adopting differential PAM4 signaling as the basis for all of the 200 Gbps/lane passive copper cable and backplane PMDs.
Note: Backplane objective is subject to Task Force adoption and WG approval
Results: Y: 80, N: 0, NMI: 5

Straw Poll #2:
I would support adopting RS(544,514,10) as the FEC encoding for all of the 200 Gbps/lane passive copper cable and backplane PMDs.
Note: Backplane objective is subject to Task Force adoption and WG approval
Results: Y: 56, N: 3, NMI: 24

Straw Poll #3:
I support a CRU bandwidth and jitter tolerance corner frequency of 4 MHz for all 802.3dj PMD/AUIs operating at KP4 FEC and 4.27 MHz for all 802.3dj with SFEC per SFEC definition in
https://www.ieee802.org/3/dj/public/23_03/patra_3dj_01b_2303.pdf (The calculation for CRU BW is based on the following fBaud/26562.5 equation)
Results: Y: 38, N: 5, NMI: 13, A: 30

During Straw Poll #3, Chair noted that KP4 was intended to mean RS544 FEC.

Straw Poll #4:
I would support using lit_3dj_01a_2305 slide 7 as the direction toward a baseline for C2C.
Results: Y: 52, N: 1, NMI: 9, A: 20

Straw Poll #5:
I support a CRU bandwidth and jitter tolerance corner frequency of 4 MHz for all 802.3dj PMD/AUIs operating at RS544 FEC (The calculation for CRU BW is based on the following fBaud/26562.5 equation)
Results: Y: 57, N: 0, NMI: 6, A: 17

Straw Poll #6:
I support a CRU bandwidth and jitter tolerance corner frequency of X MHz for all 802.3dj with SFEC per SFEC definition in
https://www.ieee802.org/3/dj/public/23_03/patra_3dj_01b_2303.pdf
A. X=4 MHz (The calculation for CRU BW is based on the following fBaud/28359.38 equation)
B. X=4.27 MHz (The calculation for CRU BW is based on the following fBaud/26562.5 equation)
C. Need more information
D. No opinion/abstain.
Results: A: 14,   B: 19,   C: 13,   D: 30

For Straw Poll #6, Chair noted that SFEC was the inner code FEC per patra_3dj_01b_2303.pdf

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Chair reviewed the agenda for Tuesday.

Meeting recessed for the day at 5:20 p.m.

16 May 2023
Meeting reconvened at 8:00 a.m. central time zone.

Chair made opening comments and reviewed the plans for the day. Chair noted an error in the agenda and would update it to version 'b'. (see: https://www.ieee802.org/3/dj/public/23_05/agenda_3cwdfdj_b_2305.pdf)

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Chair reminded participants to sign into the IEEE Meeting Attendance Tool for Task Force attendance credit. Kent Lusted noted that neither he nor the WG Recording Secretary Jon Lewis would update attendance records after the meeting ends for the day.

Chair noted that every attendee at any IEEE 802 interim meeting (Face-to-Face or Remote) must pay a fee to participate.

Chair asked participants to send proposed straw polls to him and the recording secretary.

Chair noted that he uploaded the channel contributions from Nathan Tracy and Megha Shanbhag. However, the webpage had issues and he reverted to a backup version of the page. He would update the webpage at a later time.

Presentation #16

Title	**Updated KR Channels In Support of a 200G Backplane Objective**
Presenters	Nathan Tracy
URL	https://www.ieee802.org/3/dj/public/23_05/shanbhag_3dj_02_2305.pdf

Chair noted that he received a channel contribution associated with the presentation and the channel files would be announced over the TF email reflector when posted. Author noted that these channels should replace the versions that are currently posted. Questions were asked and answered.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Presentation #17

Title	**212Gb/s Per Lane PAM4 KR Cabled Backplane Channels with Asymmetric NPC Cable Lengths**
Presenters	Jim Weaver
URL	https://www.ieee802.org/3/dj/public/23_05/weaver_3dj_01_2305.pdf

The channels associated with the contribution had been posted to the 3dj Task Force Tools and Channels website. (see: https://www.ieee802.org/3/df/public/tools/index.html)
Questions were asked and answered.

Prior to the start of the presentation from Rich Mellitz, the author had an updated presentation with editorial changes in version '01a'. It was already under the website.

Presentation #18

Title	**200 Gb/s per lane KR Backplane Objective Proposal**
Presenters	Rich Mellitz
URL	https://www.ieee802.org/3/dj/public/23_05/mellitz_3dj_01a_2305.pdf

Chair asked the electrical track chair Kent Lusted if the 3dj CSDs had been reviewed. Kent Lusted confirmed that he reviewed them and that no modifications were needed.

Chair reviewed voting in the task force. (See Slide #15) Chair noted that the straw polls would use the online Zoom tool. Motions would be taken with the Direct Vote Live tool if there was not unanimous consent. Chair noted that he reserved the right to take informative straw polls by 802.3 WG voting membership.

Straw Poll #7:
I would support adopting the backplane objectives for 200GBASE-KR1, 400BASE-KR2, 800GBASE-KR4, and 1.6TBASE-KR8 in mellitz_3dj_01a_2305, slide 13
Results: Y: 87, N: 0, A: 19

Presentation #19

Title	**Economics of Latency**
Presenters	David Ofelt
URL	https://www.ieee802.org/3/dj/public/23_05/ofelt_3dj_01_2305.pdf

Questions were asked and answered.

Break at 9:55 a.m. Resumed at 10:22 a.m.

Prior to the start of the presentation from Ali Ghiasi, the author had an updated presentation with editorial changes in version '02a'. Chair would post it to the website.

Presentation #20

Title	**Partitioning AUI C2M and C2C BERs**
Presenters	Ali Ghaisi
URL	https://www.ieee802.org/3/dj/public/23_05/ghiasi_3dj_02a_2305.pdf

Questions were asked and answered.

Prior to the start of the presentation from Adee Ran, the author had an updated presentation with editorial changes in version '01a'. Chair would post it to the website.

Presentation #21

Title	**Proposal for BER budget allocation for AUIs in Type 1 and Type 2 PHYs**
Presenters	Adee Ran
URL	https://www.ieee802.org/3/dj/public/23_05/ran_3dj_01a_2305.pdf

Questions were asked and answered.

Presentation #22

Title	**BER Targets for Type 1 and Type 2 PHYs**
Presenters	Kent Lusted and Mark Nowell
URL	https://www.ieee802.org/3/dj/public/23_05/lusted_3dj_03a_2305.pdf

There was a request to update the contribution with the 2.5E-5 BER target number from Lenin Patra's presentation and to update the figure on slide 5. Author would provide an updated version '03a'.

Questions were asked and answered.

Break at 11:58 a.m. Resumed at 1:15 p.m.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Presentation #23

Title	**FEC_I Sublayer Architecture Proposal for Type 2 PHYs**
Presenters	Xiang He
URL	https://www.ieee802.org/3/dj/public/23_05/he_3dj_01_2305.pdf

Questions were asked and answered.

Presentation #24

Title	**4x RS Codeword Interleaving Proposal for 200 GbE and 400 GbE**
Presenters	Xiang He
URL	https://www.ieee802.org/3/dj/public/23_05/he_3dj_02_2305.pdf

Questions were asked and answered.

Prior to the start of the presentation from Zvi Rechtman, the author had an updated presentation with editorial changes in version '01a'. Chair would post it to the website.

Presentation #25

Title	**Simplified Pad Insertion for Inner FEC**
Presenters	Zvi Rechtman
URL	https://www.ieee802.org/3/dj/public/23_05/rechtman_3dj_01a_2305.pdf

Arash Farhood noted that he would be giving presentation #25 instead of Lenin Patra.

Presentation #26

Title	**Various Convolutional Interleaver options for Inner FEC code (128, 20)**
Presenters	Arash Farhood
URL	https://www.ieee802.org/3/dj/public/23_05/patra_3dj_01b_2305.pdf

Author noted an error in the calculation of the PMD BER numbers on slide 10, slide 12 and the summary and would provide an updated version '01b'.

Questions were asked and answered.

Chair noted that the proposed draft liaison to the ITU was updated based on feedback and that participants should review it for consideration during closing business. (see: https://www.ieee802.org/3/dj/public/23_05/effenberger_3dj_01b_2305_Redacted.pdf)

Break at 2:51 pm. Resumed at 3:18 p.m.

Prior to the start of the presentation from Lenin Patra, the author had an updated presentation with editorial changes in version '02a'. Chair would post it to the website.

Presentation #27

Title	**25G PCSL & 100G PCSL based FEC sublayer Architecture for Inner Code**
Presenters	Lenin Patra
URL	https://www.ieee802.org/3/dj/public/23_05/patra_3dj_02a_2305.pdf

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Presentation #28

Title	**FEC Inner Code Bypass Options for 200G/L IMDD Optics**
Presenters	Brian Welch, Zvi Rechtman
URL	https://www.ieee802.org/3/dj/public/23_05/welch_3dj_03c_2305.pdf

Author noted that he had an updated version '03a' with additional supporters and would provide it to the Chair.

Questions were asked and answered.

Presentation #29

Title	**Baseline proposals for 200G/L PMD specifications for single wavelength 500m and 2km standards**

Presenters	Brian Welch
URL	https://www.ieee802.org/3/dj/public/23_05/welch_3dj_01b_2305.pdf

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Straw Poll #8:
I would support adding a 4-codeword interleaving function in 200 Gb/s per lane PMAs used with 200GBASE-R and 400GBASE-R PCS, as proposed in he_3dj_02_2305.
Results: Y: 51 , N: 5 , NMI: 23 , A: 23

Straw Poll #9:
If adopting a 4-codeword interleaving function for 200 Gb/s per lane PMA used with 200GBASE-R and 400GBASE-R PCS, I prefer the following method:
A: option 1 (delay half of the PCS lanes) on slides 6 and 7 in he_3dj_02_2305
B: option 2 (convolutional) on slide 8 in he_3dj_02_2305
C: either option 1 or option 2
D: Need more information
E: Abstain
(pick one)
Results: A: 9 , B: 2 , C: 18 , D: 39   , E: 31

Straw Poll #10:
I am supportive of the direction of patra 3dj_ 02a_2305 as the baseline Convolutional Interleaver proposal for Inner Code FEC (128,120) for 200GbE/400GbE/800GbE/1.6TbE PCS.
Results: Y: 36 , N: 12 , NMI: 26 , A: 29

Chair reviewed the plans for Wednesday.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Chair noted that the proposed draft liaison to the ITU was posted to the website and that participants should review it for consideration during closing business. (see: https://www.ieee802.org/3/dj/public/23_05/effenberger_3dj_01b_2305_Redacted.pdf)

Chair noted that Wednesday would begin with a review of the 3cw and 3df editorial reports and related bucket motions.

Kent Lusted summarized the progress on the AUI BER topics and encouraged participants to build consensus offline.

Meeting recessed for the day at 5:34 p.m.

17 May 2023
Meeting reconvened at 8:01 a.m. central time zone.

Chair made opening comments and reviewed the plans for the day. (see:
https://www.ieee802.org/3/dj/public/23_05/agenda_3cwdfdj_b_2305.pdf)

Chair noted that every attendee at any IEEE 802 interim meeting (Face-to-Face or Remote) must pay a fee to participate.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Chair reminded participants to sign into the IEEE Meeting Attendance Tool for Task Force attendance credit. Kent Lusted noted that neither he nor the WG Recording Secretary Jon Lewis would update attendance records after the meeting ends for the day.

Chair noted that the meeting website was updated with all of the updated contributions received.

Chair noted that there was an updated version '01b' from Chris Cole with technical updates. Chair asked if there was objection to hearing the updated presentation. No one responded.

Chair reviewed the plans for the plan.

Presentation #30

Title	**IEEE P802.3cw Chief Editor's Report**
Presenters	Tom Issenhuth
URL	https://www.ieee802.org/3/cw/public/23_05/issenhuth_3cw_01a_2305.pdf

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Presentation #31

Title	**IEEE P802.3ck Chief Editor's Report**
Presenters	Matt Brown

URL	https://www.ieee802.org/3/df/public/23_05/brown_3df_01_2305.pdf

Prior to motion #1, Chair asked if there would be opposition to attempt the vote by unanimous consent. No one responded.

Motion #1:	Move to adopt the proposed responses for 802.3cw D2.1 comment resolution in https://www.ieee802.org/3/cw/comments/D2p1/8023cw_D2p1_comments_bucket1_by_clause.pdf except # 103, 174, 182, 190, 192, 200
Technical (>= 75%)	
Moved by	Tom Issenhuth
Second by	Matt Brown
Results 802.3 (y/n/a)	motion passed by unanimous consent 8:22 a.m.

Prior to motion #2, Chair asked if there would be opposition to attempt the vote by unanimous consent. No one responded.

Motion #2:	Move to adopt the proposed responses for 802.3df D2.0 comment resolution in https://www.ieee802.org/3/df/comments/D2p0/8023df_D2p0_comments_bucket1_clause.pdf except # 31, 17, 30, 21, 23, 22, 95, 99, 103, 106, 105, 104, 2, 55.
Technical (>= 75%)	
Moved by	Matt Brown
Second by	Mike Dudek
Results 802.3 (y/n/a)	passed by unanimous consent 8:24 a.m.

The Vice-Chair thanked the P802.3cw and the P802.3df editorial teams for their hard work to produce the draft specifications.

Prior to the start of the presentation from Roberto Rodes, the author had an updated presentation with changes in version '02a'. The changes were updated examples, references and additional supporters. Chair asked if there was opposition to hearing the updated presentation. No one responded.

Presentation #32

Title	**Considerations on an 800G-FR4 baseline**
Presenters	Roberto Rodes
URL	https://www.ieee802.org/3/dj/public/23_05/rodes_3dj_02b_2305.pdf

Questions were asked and answered.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Presentation #33

Title	**Updates on Baseline Proposal for 800G-FR4 Objective**
Presenters	Guangcan Mi
URL	https://www.ieee802.org/3/dj/public/23_05/mi_3dj_01a_2305.pdf

Author noted an error in slide 7 with the footnote and would provide an updated version '01a'.

Questions were asked and answered.

Presentation #34

Title	**Baseline proposal for 200G/L PMD specification for 4 wavelengths over a single SMF in each direction with lengths up to at least 2km**
Presenters	Brian Welch
URL	https://www.ieee802.org/3/dj/public/23_05/welch_3dj_02a_2305.pdf

Questions were asked and answered.

Chair noted that the next agenda item was straw polls on the topics related to the morning presentations and to notify the leadership if there were straw polls for consideration.

Break at 9:57 a.m. Resumed at 10:20 a.m.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Chair noted that the proposed draft liaison to the ITU was posted to the website and that participants should review it for consideration during closing business. (see: https://www.ieee802.org/3/dj/public/23_05/effenberger_3dj_01b_2305_Redacted.pdf)

Presentation #35

Title	**802.3 SMF Channel Proposal Using Existing ITU-T Codes**
Presenters	Chris Cole
URL	https://www.ieee802.org/3/dj/public/23_05/cole_3dj_01b_2305.pdf

Questions were asked and answered.

Presentation #36

Title	**Towards an 800G-LR4 IMDD Specification Consensus - May 2023 update**
Presenters	Roberto Rodes
URL	https://www.ieee802.org/3/dj/public/23_05/rodes_3dj_01_2305.pdf

Questions were asked and answered.

Break at 11:51 a.m. Resumed at 1:16 p.m.

Chair noted that the leadership received several straw poll requests. He noted that the requests would be considered and that the leadership may combine or modify the straw polls in order to move the group forward.

Presentation #37

Title	**Feasibility Study on Baud-Rate Sampling and Equalization (BRSE) for 800G-LR1**
Presenters	Tao Gui
URL	https://www.ieee802.org/3/dj/public/23_05/gui_3dj_01a_2305.pdf

During the presentation author noted a missing reference on Slide #3 and would provide an updated version '01a'. Questions were asked and answered.

Presentation #38

Title	**Feasibility Study on O-Band Coherent 800G-LR1 & ER1**
Presenters	Sisi Tan
URL	https://www.ieee802.org/3/dj/public/23_05/gui_3dj_02_2305.pdf

Questions were asked and answered.

Presentation #39

Title	**Benefits of a Coherent Solution Tailored for 800G-LR1**
Presenters	Or Vidal
URL	https://www.ieee802.org/3/dj/public/23_05/carusone_3dj_01_2305.pdf

Questions were asked and answered.

Presentation #40

Title	**Considerations on GMP bypass for 800G-LR1/ER1**
Presenters	Haojig Wang
URL	https://www.ieee802.org/3/dj/public/23_05/wang_3dj_01a_2305.pdf

Questions were asked and answered.

Meeting break at 2:53 p.m. Meeting reconvened at 3:15 p.m.

Chair reminded face-to-face attendees of logistics for the social on Wednesday night.
Chair noted that the presentation from Tom Williams has an additional co-author and supporters. Mr. Williams would send the updated presentation to the chair.

Presentation #41

Title	**Update to oFEC-based single lambda baseline for 10km and 40km objectives**
Presenters	Tom Williams
URL	https://www.ieee802.org/3/dj/public/23_05/williams_3dj_01a_2305.pdf

Questions were asked and answered.

Chair noted that presenters may add supporters until the end of the presentation. Supporters may not be added after the presentation or via email.

Presentation #42

Title	**Logic baseline proposal (PCS and PMA) for a single Lambda coherent solution to address the 800GbE 10km and 40km SMF objectives**
Presenters	Gary Nicholl
URL	https://www.ieee802.org/3/dj/public/23_05/nicholl_3dj_01a_2305.pdf

Questions were asked and answered.

Prior to the start of the presentation from Eric Maniloff, the author had an updated presentation with changes in version '01a'. The changes were updated figures. Chair asked if there was opposition to hearing the updated presentation. No one responded.

Presentation #43

Title	**Logic baseline proposal for 800GBASE-LR1**
Presenters	Eric Maniloff
URL	https://www.ieee802.org/3/dj/public/23_05/maniloff_3dj_01a_2305.pdf

Questions were asked and answered.

Straw Poll #11:
I would support patra_3dj_01b_2303 slides 6 to 8, 13, 14, and 20 to 23 as part of the FEC approach for 800GBASE-LR4 with FEC lane rate and convolutional interleaver details to be determined later
Results: Y: 69, N: 0, A: 19

Chair reminded in-person participants of the social event.

Chair noted that there would be a late contribution from Adee Ran and co-authors with consensus on the AUI BER targets.

Chair noted that participants should review the proposed liaison to the ITU-T. He also noted that the proposed liaison to the OIF from P802.3cw would be taken off the meeting agenda and a response would be considered in July.

Meeting recessed for the day at 5:17 p.m.

18 May 2023
Meeting reconvened at 8:02 a.m. central time zone.

Chair made opening comments and reviewed the plans for the day. (see: https://www.ieee802.org/3/dj/public/23_05/agenda_3cwdfdj_c_2305.pdf)

Chair noted that there were a number of motions and straw polls planned for the day. He noted that some of the topics may be controversial and he may call extended breaks as needed.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Chair reminded participants to sign into the IEEE Meeting Attendance Tool for Task Force attendance credit.

Chair noted that every attendee at any IEEE 802 interim meeting (Face-to-Face or Remote) must pay a fee to participate.

Chair noted that the straw polls would use the online Zoom tool. Motions would be taken with the Direct Vote Live tool if there was not unanimous consent. Chair noted that he reserved the right to take informative straw polls by 802.3 WG voting membership.

Motion #3:	Move to adopt the PCS, DTE XS, and PHY XS noted on slide #4 of dambrosia_3dj_01a_2305 for all 200 Gb/s per lane signaling based PHYs for 200 GbE, 400 GbE, and 800 GbE
Technical (>= 75%)	
Moved by	Mike Dudek
Second by	Gary Nicholl
Results 802.3 (y/n/a)	passed by unanimous consent. 8:13 a.m.

Chair asked if anyone was having trouble accessing the Direct Vote Live tool for voting on motions. A few people indicated trouble. Chair asked participants having trouble to contact him for recording their votes.

Motion #4:	Move to adopt gustlin_3dj_01b_230206, slides 6-12, as the baseline for the 1.6TbE PCS/FEC
Technical (>= 75%)	
Moved by	Mark Gustlin
Second by	Adee Ran
Results 802.3 (y/n/a)	passed by unanimous consent 8:22 a.m.

Chair noted that motion #4 from the May 2023 meeting would now replace motion #10 from the January 2023 interim meeting and he would update the Task Force key motions file accordingly.

Motion #5:	Move to:
	● Adopt the following backplane objectives for 200GBASE-KR1, 400BASE-KR2, 800GBASE-KR4, and 1.6TBASE-KR8:
	    ○ Define a physical layer specification that supports 200 Gb/s operation over 1 lane over electrical backplanes supporting a die-to-die insertion loss <= 40 dB at 53.125 GHz
	    ○ Define a physical layer specification that supports 400 Gb/s operation over 2 lanes over electrical backplanes supporting a die-to-die insertion loss <= 40 dB at 53.125 GHz
	    ○ Define a physical layer specification that supports 800 Gb/s operation over 4 lanes over electrical backplanes supporting a die-to-die insertion loss <= 40 dB at 53.125 GHz
	    ○ Define a physical layer specification that supports 1.6 Tb/s operation over 8 lanes over electrical backplanes supporting a die-to-die insertion loss <= 40 dB at 53.125 GHz

Technical (>= 75%)	
Moved by	Rich Mellitz
Second by	Jim Weaver
Results 802.3 (y/n/a)	passed by unanimous consent. 8:26 a.m.

Motion #6:	Move to: ● Adopt differential PAM4 signaling as the basis for all of the 200 Gbps/lane passive copper cable and backplane PMDs and adopt RS(544,514,10) as the only FEC encoding for all of the 200 Gbps/lane passive copper cable and backplane PMDs
Technical (>= 75%)	
Moved by	Mike Li
Second by	Ali Ghiasi
Results 802.3 (y/n/a)	passed by unanimous consent. 8:30 a.m.

Chair noted that the late contribution from Adee Ran with consensus building on the AUI BER target topic. Chair asked if there was objection to hearing the contribution. No one responded.

Presentation #44

Title	Consensus proposal for AUI error requirements
Presenters	Adee Ran
URL	https://www.ieee802.org/3/dj/public/23_05/ran_3dj_02_2305.pdf

Questions were asked and answered.

Chair asked if anyone was having trouble accessing the Direct Vote Live tool for voting on straw polls. A few people indicated trouble. Chair asked participants having trouble to contact him for recording their votes.

Straw poll #12:
I would support adopting a DER0 value of 2.67e-5 (equivalent to measured BER of 4e-5 with precoding ON) for higher-loss AUIs within a PHY (BER division between C2C and C2M as well as the measurement method to be determined later)
Results (all): Y: 74 , N: 10 , A: 31
Results (802.3 voters only): Y: 63 , N: 11,   A: 25

Break at 9:40 a.m. Resumed at 10:17 a.m.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Chair would attempt to take motion #7 by unanimous consent.

Motion #7:	Move to adopt a CRU bandwidth and jitter tolerance corner frequency of 4 MHz for all 802.3dj PMD/AUIs operating at RS544 FEC (The calculation for CRU BW is based on the following fBaud/26562.5 equation)
Technical (>= 75%)	
Moved by	Ali Ghiasi
Second by	Mike Li
Results 802.3 (y/n/a)	passed by unanimous consent 10:21 a.m.

Chair asked if anyone was having trouble accessing the Direct Vote Live tool for voting on motions. A few people indicated trouble. Chair asked participants having trouble to contact him for recording their votes.

Motion #8:	Move to: Adopt a DER0 value of 2.67e-5 (equivalent to measured BER of 4e-5 with precoding ON) as the total allocation for higher-loss AUIs within a PHY (BER division between C2C and C2M as well as the measurement method to be determined later)
Technical (>= 75%)	

Moved by	Adee Ran
Second by	Kishore Kota
Results 802.3 (y/n/a)	Y: 75, N: 3, A: 20 passed 10:33 a.m.

Roll call votes record for Motion #8:

Attendee	Vote
Adam Healey	Yes
Adee Ran	Yes
Ali Ghiasi	Yes
Andras De Koos	Yes
Angela Lambert	Abstain
Arthur Marris	Yes
Ayal Shoval	Yes
Brandon Gore	Yes
Brian Welch	Yes
Cathy Liu	Yes
Charles Moorwood	Yes
Chendi Jiang	Yes
David Estes	Yes
David Malicoat	Yes
David Ofelt	Yes
Earl Parsons	Yes
Ed Ulrichs	Yes
Edward Nakamoto	Yes
Edward Sprague	Yes
Eric Bernier	Yes
Eric Kimber	Yes
Eric Maniloff	Yes

Attendee	Vote
Ernest Muhigana	Yes
Eugene Opsasnick	Yes
Eyal Lieder	Abstain
Gary Nicholl	Yes
Gerald Pepper	Yes
Golam Choudhury	Yes
Greg Le Cheminant	Abstain
Guangcan Mi	Yes
Hai-Feng Liu	Abstain
Haojie Wang	Yes
Hideki Isono	Abstain
Howard Heck	Yes
James Weaver	Yes
Jane Lim	Yes
Jeff Slavick	Yes
Jeffery Maki	Yes
John Calvin	Abstain
John Johnson	Yes
Jonathan Ingham	Abstain
Jose Castro	Yes
Junqing Sun	Abstain
Kapil Shrikhande	Abstain
Karen Liu	Yes
Karl Bois	Yes
Kenneth Jackson	Yes

Attendee	Vote
Kihong/Joshua Kim	Yes
Kishore Kota	Yes
Leon Bruckman	Yes
Liav Ben-Artsi	Yes
Limin Geng	Abstain
Mark Gustlin	Yes
Mark Sikkink	Yes
Massimo Sorbara	Abstain
Matthew Brown	Yes
Mau-Lin Wu	Yes
Michael Dudek	No
Michael Klempa	Abstain
Mike Sluyski	Yes
Mike-Peng Li	Yes
Nathan Tracy	Yes
Olindo Savi	Yes
Pei-Rong Li	Yes
Peter Del Vecchio	Abstain
Peter Stassar	Yes
Peter Wu	Yes
Piers J G Dawe	No
Pirooz Tooyserkani	Yes
Qinhui Huang	Yes
Ramana Murty	Abstain
Raymond Nering	Yes

Attendee	Vote
Richard Mellitz	Yes
Roberto Rodes	Yes
Sam Kocsis	Yes
Scott Sommers	Yes
Semmy Peng	Yes
Shawn Nicholl	Yes
Shimon Muller	Abstain
Shuang Yin	Yes
Steven Scott Gorshe	Yes
Takahito Fukushima	Yes
Takuya Ninomiya	Abstain
Thomas Huber	Yes
Thomas Palkert	Yes
Tom Issenhuth	Yes
Tomoo Takahara	Yes
Toshiaki Sakai	Yes
Ulf Parkholm	Abstain
Viet Tran	Abstain
William Klingensmith	Yes
William Simms	No
Xiang He	Yes
Xiang Liu	Yes
Yasuo Hidaka	Abstain
Yu Xu	Abstain
Yung Sung Son	Yes

Attendee	Vote
Zvi Rechtman	Yes

Motion #9:	Move to: • Adopt patra_3dj_01b_2303 slides 6 to 8, 13, 14, and 20 to 23 as part of the FEC approach for 800GBASE-LR4 with FEC lane rate and convolutional interleaver details to be determined later
Technical (>= 75%)	
Moved by	Roberto Rodes
Second by	Ali Ghiasi
Results 802.3 (y/n/a)	passed by unanimous consent. 10:37 a.m.

Straw Poll #13:

I am interested in working towards enabling an inner code FEC bypass approach for 200 G/lambda IMDD optics

A. all single wavelength

B. multi-wavelength 2km

C. none

D. NMI

E. abstain

(chicago rules)

Results: A: 76 , B: 61,   C: 19,   D: 22,   E: 11

Straw Poll #14:

I support adopting DP-16QAM modulation on a single wavelength as the basis for the following objectives:
- Define a physical layer specification that supports 800 Gb/s operation:
  - over 1 wavelength over a single SMF in each direction with lengths up to at least 10 km
  - over a single SMF in each direction with lengths up to at least 40 km

Results: Y: 75, N: 4,   A: 32

Motion #10:	Move to: • adopt DP-16QAM modulation on a single wavelength as the basis for the following objectives: ○ Define a physical layer specification that supports 800 Gb/s operation: ■ over 1 wavelength over a single SMF in each direction with lengths up to at least 10 km ■ over a single SMF in each direction with lengths up to at least 40 km
Technical (>= 75%)	
Moved by	Mark Nowell
Second by	Matt Brown

Results 802.3 (y/n/a)	passed by unanimous consent 11:30 a.m.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Break at 11:32 a.m. Resumed at 1:16 p.m.

Chair reminded participants to sign into IMAT for Task Force and IEEE 802.3 Working Group attendance.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Presentation #45:

Title	**IEEE history on 10 km and 40km PMD interoperation**
Presenters	Mark Nowell
URL	https://www.ieee802.org/3/dj/public/23_05/nowell_3dj_02_2305.pdf

Straw Poll #15:
I support 800GBASE-LR1 and 800GBASE-ER1 sharing common logic (PCS/FEC) and optical wavelengths so they can interoperate under defined conditions.
Results: Y: 35, N: 32, NMI: 7, A: 26

Straw Poll #16:
I support 800GBASE-LR1 and 800GBASE-ER1 sharing common logic (PCS/FEC)
Y: 49 , N: 19, NMI: 8,   A: 26

There was a request for participants that voted no or need more information in straw poll #16 to share thoughts. Inputs were provided.

Vice Chair reminded participants to declare their affiliation in the online meeting tool. Failure to declare affiliation would result in expulsion from the meeting.

Straw Poll #17:
I am supportive of the direction of maniloff_3dj_01a_2305 (slides 4-12) as the baseline FEC proposal for the single wavelength 10 km 800Gb/s optical PMD.
Results: Y: 44, N: 13,   NMI: 13,   A: 34

Straw Poll #18:

I would support adopting baselines for 800GBASE-LR1 and 800GBASE-ER1 based on oFEC as proposed in williams_3dj_01a_2305 and nicholl_3dj_01a_2305

Results: Y: 24, N: 38, NMI: 7, A: 36

Break at 2:55 p.m. Resumed at 3:15 p.m.

Chair reviewed the proposed liaison to ITU. (see: https://www.ieee802.org/3/dj/public/23_05/effenberger_3dj_01b_2305_Redacted.pdf) Changes were made and saved. (see: https://www.ieee802.org/3/dj/public/23_05/IEEE_802d3_to_ITU_3df_2305_draft_redacted.pdf)

Motion #11:	Move that the P802.3dj Task Force approve: ● IEEE_802d3_to_ITU_3df_2305_draft_redacted.pdf with editorial license granted to the Chair (or his appointed agent) as a liaison communication from the IEEE 802.3 Working Group to ITU-T SG 15.
Technical (>= 75%)	
Moved by	Tom Huber
Second by	Peter Stassar
Results 802.3 (y/n/a)	Passed by unanimous consent 3:51 p.m.

Chair reviewed future meetings (see slide #27). He reminded participants of the P802.3df electronic interim for Draft 2.0 comment resolution. He reminded participants of the P802.3cw electronic interim for Draft 2.1 comment resolution. He noted that some of the meetings may be canceled pending progress.

Chair noted that the meeting agenda was complete.

Meeting adjourned at 3:56 p.m.

Attendees

15 May 2023

Date	Name	Employer	Affiliation
5/15	Beauregard, Francois	Belden Canada ULC	Belden
5/15	Ben Amram, Haim		Retym
5/15	Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/15	Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
5/15	Bois, Karl	NVIDIA Corporation	NVIDIA Corporation
5/15	Boyer, Rich	Aptiv - Signal and Power Solutions	Aptiv Signal and Power Solutions
5/15	Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
5/15	Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada
5/15	Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Calvin, John	Keysight Technologies	Keysight Technologies
5/15	Cassan, Dave	Alphawave	Alphawave
5/15	Castro, Jose	Panduit	Panduit Corp.
5/15	Chan, Jason		Arista Networks
5/15	Chan Carusone, Anthony		Alphawave Semi; University of Toronto
5/15	Chang, Yongmao	Inphi Corporation	Source Photonics
5/15	Choudhury, Golam	OFS	OFS
5/15	Cox, Ian		Broadcom Corporation
5/15	D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
5/15	Dawe, Piers J G	NVIDIA	Nvidia
5/15	de Koos, Andras	Microchip Technology Inc	Microchip Technology, Inc.

Date	Name	Employer	Affiliation
5/15	Del Vecchio, Peter		Broadcom Corporation
5/15	Dube, Kathryn	UNH-IOL	UNH-IOL
5/15	Dudek, Michael	Marvell	Marvell
5/15	Estes, David	Spirent Communications	Spirent Communications
5/15	Fellhauer, Felix	Robert Bosch GmbH	Robert Bosch GmbH
5/15	Feyh, German	Broadcom Corporation	Broadcom Corporation
5/15	FUKUSHIMA, TAKAHITO	Dexerials Corporation	Dexerials
5/15	Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
5/15	Gore, Brandon	Samtec, Inc.	Samtec, Inc.
5/15	Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
5/15	Gu, Tao	Centec Networks (Suzhou) Co., Ltd.	Centec
5/15	Gui, Tao		Huawei Technologies Co., Ltd
5/15	Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Healey, Adam	Broadcom Inc.	Broadcom Inc.
5/15	Heck, Howard	Intel	Intel
5/15	Heimbuch, Mark		Cisco Systems, Inc.
5/15	Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
5/15	HIRASE, HIDENARI	AGC Inc	AGC.Inc
5/15	Hozeska, Charles	Cernitin Solutions	Cernitin Solutions
5/15	Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Huber, Thomas	Nokia	Nokia

Date	Name	Employer	Affiliation
5/15	Hutchins, Jeff	Ranovus	Ranovus
5/15	Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
5/15	Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
5/15	Jiang, Chendi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Jiang, Chenhui	Sicoya	Sicoya GmbH
5/15	Jimenez, Andrew	Anixter Inc.	Anixter Inc.
5/15	Johnson, John	Broadcom Corporation	Broadcom Corporation
5/15	Jonsson, Ragnar	Marvell Semiconductor, Inc.	Marvell
5/15	Kimber, Eric	Semtech Ltd	Semtech Ltd
5/15	Klempa, Michael	Alphawave Semi	Alphawave Semi
5/15	Klingensmith, William	U.S. Federal Government	DoD
5/15	Koch, Lavi		Lavi Koch Nvidia
5/15	Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
5/15	Kondo, Taiji	MegaChips Corporation	Dexerials Corporation
5/15	Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/15	Kurashima, Kazuyoshi	AGC	AGC
5/15	Lackner, Hans	QoSCom GmbH	QoSCom GmbH
5/15	Lambert, Angela	Corning Incorporated	Corning Incorporated
5/15	Lawson, Matthew	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
5/15	Lewis, Jon	Dell Technologies	Dell Technologies
5/15	Li, Jing	YOFC	YOFC
5/15	Li, Mike-Peng	Intel	Intel

Date	Name	Employer	Affiliation
5/15	Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
5/15	Lieder, Eyal	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/15	Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	Liu, Cathy	Broadcom Corporation	Broadcom Corporation
5/15	Liu, Hai-Feng	HG Genuine	HG Genuine
5/15	Liu, Karen	Nubis Communications	Nubis Communications
5/15	LIU, XIANG		Huawei Technologies Co., Ltd
5/15	Lu, Yuchun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Lusted, Kent	Intel	Intel
5/15	Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
5/15	Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
5/15	Maniloff, Eric	Ciena Corporation	Ciena Corporation
5/15	Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
5/15	Martino, Kjersti	Inneos	Inneos
5/15	Maruyama, Takuto		Mitsubishi Electric US, Inc
5/15	Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
5/15	Moorwood, Charles	Keysight Technologies	Keysight Technologies
5/15	Muhigana, Ernest		Lumentum
5/15	Muller, Shimon	Enfabrica Corp.	Enfabrica
5/15	MURAKAMI, YUKI		Fujitsu Limited
5/15	Murty, Ramana	Broadcom Inc.	Broadcom Corporation
5/15	Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
5/15	Nakamoto, Edward	Spirent Communications	Spirent Communications
5/15	Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	Nicholl, Shawn	Xilinx	Advanced Micro Devices (AMD)

Date	Name	Employer	Affiliation
5/15	Ninomiya, Takuya		Senko Advanced Components
5/15	Noujeim, Leesa	Google	Google
5/15	Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
5/15	Oi, Shigehiro		ICB-G
5/15	Omori, Kumi	NEC Corporation	NEC Corporation
5/15	Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
5/15	Palkert, Thomas	Macom, Samtec	Samtec-Macom
5/15	PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
5/15	Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson
5/15	Parsons, Earl	CommScope, Inc.	CommScope, Inc.
5/15	Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
5/15	peng, semmy		Huawei Technologies Co., Ltd
5/15	Pepper, Gerald	Keysight Technologies	Keysight Technologies
5/15	Piehler, David	Dell Technologies	Dell
5/15	Rabinovich, Rick	Keysight Technologies	Keysight Technologies
5/15	Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	Rechtman, Zvi	NVIDIA	NVIDIA
5/15	Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Riani, Jamal		Marvell Semiconductor, Inc.
5/15	Rodes, Roberto	II-VI	II-VI
5/15	Sakai, Toshiaki	Socionext Inc.	socionext
5/15	Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
5/15	SAWANO, Hiroshi	OITDA (Optoelectronics Industry and Technology Development Association)	OITDA

Date	Name	Employer	Affiliation
5/15	Sekel, Steve		Wilder Technologies
5/15	Shah, Anup	Siemens Corporation	Siemens EDA
5/15	Shanbhag, Megha	Tyco	TE Connectivity
5/15	She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
5/15	Sheffi, Nir		Banias Labs
5/15	Shoval, Ayal	Synopsys, Inc.	Synopsys, Inc.
5/15	Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/15	Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
5/15	Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
5/15	Simms, William	NVIDIA Corporation	NVIDIA Corporation
5/15	Sinn, Peter		Alphawave IP
5/15	Slavick, Jeff	Broadcom Inc	Broadcom Inc
5/15	Sluyski, MIke		Cisco Systems, Inc.
5/15	Sommers, Scott	Molex LLC	Molex Incorporated
5/15	Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
5/15	Sprague, Edward	Infinera Corporation	Infinera Corporation
5/15	Sun, Junqing	Credo Semiconductor	Credo Semiconductor
5/15	TAN, SISI		Huawei Technologies Co., Ltd
5/15	Terada, Masaru	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
5/15	Theodoras, James	HG Genuine	HG Genuine
5/15	Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
5/15	Torres, Luis	Knowledge Development for Plastic Optical Fiber	Knowledge Development for Plastic Optical Fiber
5/15	Tracy, Nathan	TE Connectivity	TE Connectivity
5/15	Tran, Viet	Keysight Technologies	Keysight Technologies

Date	Name	Employer	Affiliation
5/15	Tsuzaki, Nozomi		Independent
5/15	Ulrichs, Ed	Intel	Intel
5/15	Vidal, Or		Alphawave Semi
5/15	Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
5/15	Watanabe, Yojiro		Mitsubishi Electric US, Inc.
5/15	Weaver, James	Arista Networks	Arista Networks
5/15	Welch, Brian	Cisco Systems, Inc.	Luxtera
5/15	Wingrove, Michael	Ciena Corporation	Ciena Corporation
5/15	Wong, Henry		Alphawave Semi
5/15	Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
5/15	Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/15	Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Yin, Shuang		Google
5/15	Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/15	Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

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Date	Name	Employer	Affiliation
5/16	Beauregard, Francois	Belden Canada ULC	Belden
5/16	Ben Amram, Haim		Retym
5/16	Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/16	Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
5/16	Bois, Karl	NVIDIA Corporation	NVIDIA Corporation

Date	Name	Employer	Affiliation
5/16	Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
5/16	Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada
5/16	Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Calvin, John	Keysight Technologies	Keysight Technologies
5/16	Cassan, Dave	Alphawave	Alphawave
5/16	Castro, Jose	Panduit	Panduit Corp.
5/16	Chan, Jason		Arista Networks
5/16	Chan Carusone, Anthony		Alphawave Semi; University of Toronto
5/16	Chang, Yongmao	Inphi Corporation	Source Photonics
5/16	Choudhury, Golam	OFS	OFS
5/16	Cox, Ian		Broadcom Corporation
5/16	D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
5/16	Dawe, Piers J G	NVIDIA	Nvidia
5/16	de Koos, Andras	Microchip Technology Inc	Microchip Technology, Inc.
5/16	Del Vecchio, Peter		Broadcom Corporation
5/16	Dube, Kathryn	UNH-IOL	UNH-IOL
5/16	Dudek, Michael	Marvell	Marvell
5/16	Effenberger, Frank	Futurewei Technologies	Futurewei Technologies
5/16	Estes, David	Spirent Communications	Spirent Communications
5/16	Farhoodfar, Arash	Inphi Corporation	Inphi Corporation
5/16	Fellhauer, Felix	Robert Bosch GmbH	Robert Bosch GmbH
5/16	Feyh, German	Broadcom Corporation	Broadcom Corporation
5/16	FUKUSHIMA, TAKAHITO	Dexerials Corporation	Dexerials
5/16	Fuller, Paul		Marvell

Date	Name	Employer	Affiliation
5/16	Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
5/16	Gore, Brandon	Samtec, Inc.	Samtec, Inc.
5/16	Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
5/16	Gu, Tao	Centec Networks (Suzhou) Co., Ltd.	Centec
5/16	Gui, Tao		Huawei Technologies Co., Ltd
5/16	Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Hajduczenia, Marek	Charter Communications	Charter Communications
5/16	He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Healey, Adam	Broadcom Inc.	Broadcom Inc.
5/16	Heck, Howard	Intel	Intel
5/16	Heimbuch, Mark		Cisco Systems, Inc.
5/16	Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
5/16	HIRASE, HIDENARI	AGC Inc	AGC.Inc
5/16	Hozeska, Charles	Cernitin Solutions	Cernitin Solutions
5/16	Huang, Howard		Synopsys, Inc.
5/16	Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Huber, Thomas	Nokia	Nokia
5/16	Hutchins, Jeff	Ranovus	Ranovus
5/16	Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
5/16	Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd

Date	Name	Employer	Affiliation
5/16	Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
5/16	Jiang, Chendi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Jiang, Chenhui	Sicoya	Sicoya GmbH
5/16	Johnson, John	Broadcom Corporation	Broadcom Corporation
5/16	Jonsson, Ragnar	Marvell Semiconductor, Inc.	Marvell
5/16	Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
5/16	Kimber, Eric	Semtech Ltd	Semtech Ltd
5/16	Klempa, Michael	Alphawave Semi	Alphawave Semi
5/16	Klingensmith, William	U.S. Federal Government	DoD
5/16	Koch, Lavi		Lavi Koch Nvidia
5/16	Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
5/16	Kondo, Taiji	MegaChips Corporation	Dexerials Corporation
5/16	Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/16	Kurashima, Kazuyoshi	AGC	AGC
5/16	Lambert, Angela	Corning Incorporated	Corning Incorporated
5/16	Lawson, Matthew	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
5/16	Li, Mike-Peng	Intel	Intel
5/16	Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
5/16	Lieder, Eyal	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/16	Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Lin, Youxi	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Co., Ltd
5/16	Liu, Cathy	Broadcom Corporation	Broadcom Corporation

Date	Name	Employer	Affiliation
5/16	Liu, Hai-Feng	HG Genuine	HG Genuine
5/16	Liu, Karen	Nubis Communications	Nubis Communications
5/16	LIU, XIANG		Huawei Technologies Co., Ltd
5/16	Lu, Yuchun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
5/16	Lusted, Kent	Intel	Intel
5/16	Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
5/16	Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
5/16	Maniloff, Eric	Ciena Corporation	Ciena Corporation
5/16	Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
5/16	Maruyama, Takuto		Mitsubishi Electric US, Inc
5/16	Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
5/16	mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Moorwood, Charles	Keysight Technologies	Keysight Technologies
5/16	Muhigana, Ernest		Lumentum
5/16	Muller, Shimon	Enfabrica Corp.	Enfabrica
5/16	MURAKAMI, YUKI		Fujitsu Limited
5/16	Murty, Ramana	Broadcom Inc.	Broadcom Corporation
5/16	Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
5/16	Nakamoto, Edward	Spirent Communications	Spirent Communications
5/16	Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Nicholl, Shawn	Xilinx	Advanced Micro Devices (AMD)
5/16	Ninomiya, Takuya		Senko Advanced Components
5/16	Noujeim, Leesa	Google	Google

Date	Name	Employer	Affiliation
5/16	Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
5/16	Oi, Shigehiro		ICB-G
5/16	Omori, Kumi	NEC Corporation	NEC Corporation
5/16	Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
5/16	Palkert, Thomas	Macom, Samtec	Samtec-Macom
5/16	PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
5/16	Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson
5/16	Parsons, Earl	CommScope, Inc.	CommScope, Inc.
5/16	Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
5/16	Patra, lenin	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/16	peng, semmy		Huawei Technologies Co., Ltd
5/16	Pepper, Gerald	Keysight Technologies	Keysight Technologies
5/16	Piehler, David	Dell Technologies	Dell
5/16	Rabinovich, Rick	Keysight Technologies	Keysight Technologies
5/16	Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Rechtman, Zvi	NVIDIA	NVIDIA
5/16	Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Riani, Jamal		Marvell Semiconductor, Inc.
5/16	Rodes, Roberto	II-VI	II-VI
5/16	Sakai, Toshiaki	Socionext Inc.	socionext
5/16	Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
5/16	SAWANO, Hiroshi	OITDA (Optoelectronics Industry and Technology Development Association)	OITDA
5/16	Sekel, Steve		Wilder Technologies

Date	Name	Employer	Affiliation
5/16	Shah, Anup	Siemens Corporation	Siemens EDA
5/16	Shanbhag, Megha	Tyco	TE Connectivity
5/16	She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
5/16	Sheffi, Nir		Banias Labs
5/16	Shoval, Ayal	Synopsys, Inc.	Synopsys, Inc.
5/16	Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/16	Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
5/16	Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
5/16	Simms, William	NVIDIA Corporation	NVIDIA Corporation
5/16	Sinn, Peter		Alphawave IP
5/16	sisk, jason	University of New Hampshire InterOperability Laboratory (UNH-IOL)	University of New Hampshire InterOperability Laboratory (UNH-IOL)
5/16	Slavick, Jeff	Broadcom Inc	Broadcom Inc
5/16	Sluyski, MIke		Cisco Systems, Inc.
5/16	Sommers, Scott	Molex LLC	Molex Incorporated
5/16	Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
5/16	Souvignier, Tom	Broadcom Corporation	Broadcom Corporation
5/16	Sprague, Edward	Infinera Corporation	Infinera Corporation
5/16	Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	SU, CHANGZHENG		Huawei Technologies Co., Ltd
5/16	Sun, Junqing	Credo Semiconductor	Credo Semiconductor
5/16	TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
5/16	TAN, SISI		Huawei Technologies Co., Ltd
5/16	Terada, Masaru	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC

Date	Name	Employer	Affiliation
5/16	Theodoras, James	HG Genuine	HG Genuine
5/16	Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Torres, Luis	Knowledge Development for Plastic Optical Fiber	Knowledge Development for Plastic Optical Fiber
5/16	Tracy, Nathan	TE Connectivity	TE Connectivity
5/16	Tran, Viet	Keysight Technologies	Keysight Technologies
5/16	Tsuzaki, Nozomi		Independent
5/16	Ulrichs, Ed	Intel	Intel
5/16	Vidal, Or		Alphawave Semi
5/16	Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
5/16	Weaver, James	Arista Networks	Arista Networks
5/16	Welch, Brian	Cisco Systems, Inc.	Luxtera
5/16	Williams, Tom	Cisco Systems, Inc.	Cisco Systems, Inc.
5/16	Wingrove, Michael	Ciena Corporation	Ciena Corporation
5/16	Wong, Henry		Alphawave Semi
5/16	Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
5/16	Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/16	Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/16	Yin, Shuang		Google

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Date	Name	Employer	Affiliation
5/17	Ben Amram, Haim		Retym
5/17	Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/17	Bernier, Eric	Huawei Technologies Canada	Huawei Technologies Canada Co., Ltd.

Date	Name	Employer	Affiliation
		Co., Ltd.	
5/17	Bois, Karl	NVIDIA Corporation	NVIDIA Corporation
5/17	Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
5/17	Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada
5/17	Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Calvin, John	Keysight Technologies	Keysight Technologies
5/17	Cassan, Dave	Alphawave	Alphawave
5/17	Castro, Jose	Panduit	Panduit Corp.
5/17	Chan, Jason		Arista Networks
5/17	Chan Carusone, Anthony		Alphawave Semi; University of Toronto
5/17	Chang, Yongmao	Inphi Corporation	Source Photonics
5/17	cheng, weiqiang	China Mobile Limited	China Mobile Limited
5/17	Cole, Christopher R	Finisar Corporation	Finisar Corporation
5/17	Cox, Ian		Broadcom Corporation
5/17	D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
5/17	Dawe, Piers J G	NVIDIA	Nvidia
5/17	de Koos, Andras	Microchip Technology Inc	Microchip Technology, Inc.
5/17	Del Vecchio, Peter		Broadcom Corporation
5/17	Dube, Kathryn	UNH-IOL	UNH-IOL
5/17	Dudek, Michael	Marvell	Marvell
5/17	Effenberger, Frank	Futurewei Technologies	Futurewei Technologies
5/17	Estes, David	Spirent Communications	Spirent Communications
5/17	Farhoodfar, Arash	Inphi Corporation	Inphi Corporation
5/17	FUKUSHIMA, TAKAHITO	Dexerials Corporation	Dexerials

Date	Name	Employer	Affiliation
5/17	Fuller, Paul		Marvell
5/17	Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
5/17	Gore, Brandon	Samtec, Inc.	Samtec, Inc.
5/17	Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
5/17	Gui, Tao		Huawei Technologies Co., Ltd
5/17	Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Healey, Adam	Broadcom Inc.	Broadcom Inc.
5/17	Heck, Howard	Intel	Intel
5/17	Heimbuch, Mark		Cisco Systems, Inc.
5/17	Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
5/17	Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Huber, Thomas	Nokia	Nokia
5/17	Hutchins, Jeff	Ranovus	Ranovus
5/17	Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
5/17	Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
5/17	Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
5/17	Jiang, Chendi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Jiang, Chenhui	Sicoya	Sicoya GmbH
5/17	Jimenez, Andrew	Anixter Inc.	Anixter Inc.

Date	Name	Employer	Affiliation
5/17	Johnson, John	Broadcom Corporation	Broadcom Corporation
5/17	Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
5/17	Kimber, Eric	Semtech Ltd	Semtech Ltd
5/17	Klempa, Michael	Alphawave Semi	Alphawave Semi
5/17	Klingensmith, William	U.S. Federal Government	DoD
5/17	Koch, Lavi		Lavi Koch Nvidia
5/17	Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
5/17	Kondo, Taiji	MegaChips Corporation	Dexerials Corporation
5/17	Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/17	Lambert, Angela	Corning Incorporated	Corning Incorporated
5/17	Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
5/17	Lawson, Matthew	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
5/17	Li, Mike-Peng	Intel	Intel
5/17	Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
5/17	Lieder, Eyal	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/17	Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	Lin, Youxi	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Co., Ltd
5/17	Liu, Cathy	Broadcom Corporation	Broadcom Corporation
5/17	Liu, Hai-Feng	HG Genuine	HG Genuine
5/17	Liu, Karen	Nubis Communications	Nubis Communications
5/17	LIU, XIANG		Huawei Technologies Co., Ltd
5/17	Lu, Yuchun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies

Date	Name	Employer	Affiliation
5/17	Lusted, Kent	Intel	Intel
5/17	Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
5/17	Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
5/17	Maniloff, Eric	Ciena Corporation	Ciena Corporation
5/17	Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
5/17	Maruyama, Takuto		Mitsubishi Electric US, Inc
5/17	Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
5/17	mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Moorwood, Charles	Keysight Technologies	Keysight Technologies
5/17	Muhigana, Ernest		Lumentum
5/17	Muller, Shimon	Enfabrica Corp.	Enfabrica
5/17	MURAKAMI, YUKI		Fujitsu Limited
5/17	Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
5/17	Nakamoto, Edward	Spirent Communications	Spirent Communications
5/17	Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	Nicholl, Shawn	Xilinx	Advanced Micro Devices (AMD)
5/17	Ninomiya, Takuya		Senko Advanced Components
5/17	Noujeim, Leesa	Google	Google
5/17	Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
5/17	Omori, Kumi	NEC Corporation	NEC Corporation
5/17	Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
5/17	Palkert, Thomas	Macom, Samtec	Samtec-Macom
5/17	PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
5/17	Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson

Date	Name	Employer	Affiliation
5/17	Parsons, Earl	CommScope, Inc.	CommScope, Inc.
5/17	Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
5/17	Patra, lenin	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/17	peng, semmy		Huawei Technologies Co., Ltd
5/17	Pepper, Gerald	Keysight Technologies	Keysight Technologies
5/17	Piehler, David	Dell Technologies	Dell
5/17	Rabinovich, Rick	Keysight Technologies	Keysight Technologies
5/17	Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	Rechtman, Zvi	NVIDIA	NVIDIA
5/17	Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Riani, Jamal		Marvell Semiconductor, Inc.
5/17	Rodes, Roberto	II-VI	II-VI
5/17	Sakai, Toshiaki	Socionext Inc.	socionext
5/17	Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
5/17	SAWANO, Hiroshi	OITDA (Optoelectronics Industry and Technology Development Association)	OITDA
5/17	Sekel, Steve		Wilder Technologies
5/17	Shah, Anup	Siemens Corporation	Siemens EDA
5/17	Shanbhag, Megha	Tyco	TE Connectivity
5/17	She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
5/17	Sheffi, Nir		Banias Labs
5/17	Shoval, Ayal	Synopsys, Inc.	Synopsys, Inc.
5/17	Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
5/17	Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
5/17	Simms, William	NVIDIA Corporation	NVIDIA Corporation

Date	Name	Employer	Affiliation
5/17	Sinn, Peter		Alphawave IP
5/17	Slavick, Jeff	Broadcom Inc	Broadcom Inc
5/17	Sluyski, MIke		Cisco Systems, Inc.
5/17	Sommers, Scott	Molex LLC	Molex Incorporated
5/17	Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
5/17	Souvignier, Tom	Broadcom Corporation	Broadcom Corporation
5/17	Sprague, Edward	Infinera Corporation	Infinera Corporation
5/17	Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	SU, CHANGZHENG		Huawei Technologies Co., Ltd
5/17	Sun, Junqing	Credo Semiconductor	Credo Semiconductor
5/17	TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
5/17	TAN, SISI		Huawei Technologies Co., Ltd
5/17	Terada, Masaru	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
5/17	Theodoras, James	HG Genuine	HG Genuine
5/17	Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
5/17	Tracy, Nathan	TE Connectivity	TE Connectivity
5/17	Tran, Viet	Keysight Technologies	Keysight Technologies
5/17	Ulrichs, Ed	Intel	Intel
5/17	Vidal, Or		Alphawave Semi
5/17	Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
5/17	Watanabe, Yojiro		Mitsubishi Electric US, Inc.
5/17	Weaver, James	Arista Networks	Arista Networks
5/17	Wey, Jun Shan	Verizon Communications	Verizon Communications
5/17	Williams, Tom	Cisco Systems, Inc.	Cisco Systems, Inc.

Date	Name	Employer	Affiliation
5/17	Wingrove, Michael	Ciena Corporation	Ciena Corporation
5/17	Wong, Henry		Alphawave Semi
5/17	Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
5/17	Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/17	Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/17	Yin, Shuang		Google
5/17	Zhang, Bo	Marvell Technology, Inc	Marvell Technology, Inc

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Date	Name	Employer	Affiliation
5/18	BARSKY, greg		Broadcom Corporation
5/18	Beauregard, Francois	Belden Canada ULC	Belden
5/18	Ben Amram, Haim		Retym
5/18	Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/18	Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
5/18	Bois, Karl	NVIDIA Corporation	NVIDIA Corporation
5/18	Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
5/18	Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Calvin, John	Keysight Technologies	Keysight Technologies
5/18	Cassan, Dave	Alphawave	Alphawave
5/18	Castro, Jose	Panduit	Panduit Corp.
5/18	Chan, Jason		Arista Networks
5/18	Chan Carusone, Anthony		Alphawave Semi; University of Toronto

Date	Name	Employer	Affiliation
5/18	Chang, Yongmao	Inphi Corporation	Source Photonics
5/18	Choudhury, Golam	OFS	OFS
5/18	Cox, Ian		Broadcom Corporation
5/18	D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
5/18	Dawe, Piers J G	NVIDIA	Nvidia
5/18	de Koos, Andras	Microchip Technology Inc	Microchip Technology, Inc.
5/18	Del Vecchio, Peter		Broadcom Corporation
5/18	Diminico, Christopher	M C Communications, LLC	Panduit Corp.
5/18	Dube, Kathryn	UNH-IOL	UNH-IOL
5/18	Dudek, Michael	Marvell	Marvell
5/18	Estes, David	Spirent Communications	Spirent Communications
5/18	FUKUSHIMA, TAKAHITO	Dexerials Corporation	Dexerials
5/18	Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
5/18	Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
5/18	Graba, James	Broadcom Corporation	Broadcom Corporation
5/18	Gu, Tao	Centec Networks (Suzhou) Co., Ltd.	Centec
5/18	Gui, Tao		Huawei Technologies Co., Ltd
5/18	Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Healey, Adam	Broadcom Inc.	Broadcom Inc.
5/18	Heck, Howard	Intel	Intel

Date	Name	Employer	Affiliation
5/18	Heimbuch, Mark		Cisco Systems, Inc.
5/18	Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
5/18	HIRASE, HIDENARI	AGC Inc	AGC.Inc
5/18	Hozeska, Charles	Cernitin Solutions	Cernitin Solutions
5/18	Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Huber, Thomas	Nokia	Nokia
5/18	Hutchins, Jeff	Ranovus	Ranovus
5/18	Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
5/18	Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
5/18	Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
5/18	Jiang, Chendi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Jiang, Chenhui	Sicoya	Sicoya GmbH
5/18	Johnson, John	Broadcom Corporation	Broadcom Corporation
5/18	Jonsson, Ragnar	Marvell Semiconductor, Inc.	Marvell
5/18	Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
5/18	Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
5/18	Kimber, Eric	Semtech Ltd	Semtech Ltd
5/18	Klempa, Michael	Alphawave Semi	Alphawave Semi
5/18	Klingensmith, William	U.S. Federal Government	DoD
5/18	Koch, Lavi		Lavi Koch Nvidia
5/18	Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
5/18	Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.

Date	Name	Employer	Affiliation
5/18	Kurashima, Kazuyoshi	AGC	AGC
5/18	Lackner, Hans	QoSCom GmbH	QoSCom GmbH
5/18	Lambert, Angela	Corning Incorporated	Corning Incorporated
5/18	Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
5/18	Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
5/18	Li, Mike-Peng	Intel	Intel
5/18	Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
5/18	Lieder, Eyal	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/18	Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Lin, Youxi	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Co., Ltd
5/18	Liu, Cathy	Broadcom Corporation	Broadcom Corporation
5/18	Liu, Hai-Feng	HG Genuine	HG Genuine
5/18	Liu, Karen	Nubis Communications	Nubis Communications
5/18	LIU, XIANG		Huawei Technologies Co., Ltd
5/18	Lu, Yuchun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
5/18	Lusted, Kent	Intel	Intel
5/18	Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
5/18	Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
5/18	Maniloff, Eric	Ciena Corporation	Ciena Corporation
5/18	Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
5/18	Maruyama, Takuto		Mitsubishi Electric US, Inc
5/18	Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
5/18	mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Date	Name	Employer	Affiliation
5/18	Moorwood, Charles	Keysight Technologies	Keysight Technologies
5/18	Muhigana, Ernest		Lumentum
5/18	Muller, Shimon	Enfabrica Corp.	Enfabrica
5/18	MURAKAMI, YUKI		Fujitsu Limited
5/18	Murty, Ramana	Broadcom Inc.	Broadcom Corporation
5/18	Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
5/18	Nakamoto, Edward	Spirent Communications	Spirent Communications
5/18	Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Nicholl, Shawn	Xilinx	Advanced Micro Devices (AMD)
5/18	Ninomiya, Takuya		Senko Advanced Components
5/18	Noujeim, Leesa	Google	Google
5/18	Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
5/18	Omori, Kumi	NEC Corporation	NEC Corporation
5/18	Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
5/18	Palkert, Thomas	Macom, Samtec	Samtec-Macom
5/18	PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
5/18	Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson
5/18	Parsons, Earl	CommScope, Inc.	CommScope, Inc.
5/18	Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
5/18	Patel, Harsh	Amphenol ICC	Amphenol Corporation
5/18	Patra, lenin	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/18	peng, semmy		Huawei Technologies Co., Ltd
5/18	Pepper, Gerald	Keysight Technologies	Keysight Technologies

Date	Name	Employer	Affiliation
5/18	Piehler, David	Dell Technologies	Dell
5/18	Rabinovich, Rick	Keysight Technologies	Keysight Technologies
5/18	Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Rechtman, Zvi	NVIDIA	NVIDIA
5/18	Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Renteria, Victor	Bel Fuse	Bel Fuse
5/18	Riani, Jamal		Marvell Semiconductor, Inc.
5/18	Rodes, Roberto	II-VI	II-VI
5/18	Sakai, Toshiaki	Socionext Inc.	socionext
5/18	Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
5/18	SAWANO, Hiroshi	OITDA (Optoelectronics Industry and Technology Development Association)	OITDA
5/18	Sekel, Steve		Wilder Technologies
5/18	Shah, Anup	Siemens Corporation	Siemens EDA
5/18	Shanbhag, Megha	Tyco	TE Connectivity
5/18	She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
5/18	Sheffi, Nir		Banias Labs
5/18	Shoval, Ayal	Synopsys, Inc.	Synopsys, Inc.
5/18	Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/18	Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
5/18	Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
5/18	Simms, William	NVIDIA Corporation	NVIDIA Corporation
5/18	Sinn, Peter		Alphawave IP
5/18	Slavick, Jeff	Broadcom Inc	Broadcom Inc
5/18	Sluyski, MIke		Cisco Systems, Inc.

Date	Name	Employer	Affiliation
5/18	Sommers, Scott	Molex LLC	Molex Incorporated
5/18	Son, Yung Sung	Optomind Inc	Optomind Inc
5/18	Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
5/18	Souvignier, Tom	Broadcom Corporation	Broadcom Corporation
5/18	Sprague, Edward	Infinera Corporation	Infinera Corporation
5/18	Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	SU, CHANGZHENG		Huawei Technologies Co., Ltd
5/18	Sun, Junqing	Credo Semiconductor	Credo Semiconductor
5/18	TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
5/18	TAN, SISI		Huawei Technologies Co., Ltd
5/18	Terada, Masaru	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
5/18	Theodoras, James	HG Genuine	HG Genuine
5/18	Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Tracy, Nathan	TE Connectivity	TE Connectivity
5/18	Tran, Viet	Keysight Technologies	Keysight Technologies
5/18	Tsuzaki, Nozomi		Independent
5/18	Vidal, Or		Alphawave Semi
5/18	Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
5/18	Watanabe, Yojiro		Mitsubishi Electric US, Inc.
5/18	Weaver, James	Arista Networks	Arista Networks
5/18	Welch, Brian	Cisco Systems, Inc.	Luxtera
5/18	Wey, Jun Shan	Verizon Communications	Verizon Communications
5/18	Williams, Tom	Cisco Systems, Inc.	Cisco Systems, Inc.
5/18	Wingrove, Michael	Ciena Corporation	Ciena Corporation

Date	Name	Employer	Affiliation
5/18	Wong, Henry		Alphawave Semi
5/18	Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
5/18	Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
5/18	Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Yin, Shuang		Google
5/18	Zhang, Bo	Marvell Technology, Inc	Marvell Technology, Inc
5/18	Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
5/18	Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd